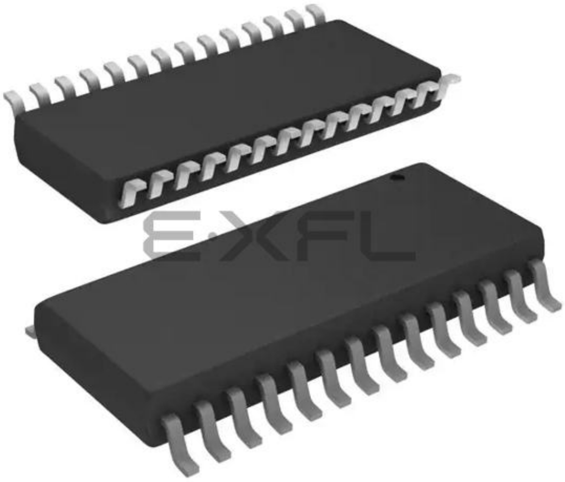
Microchip Technology - PIC16C57CT-04/SO Datasheet



What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	20
Program Memory Size	3KB (2K x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	72 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c57ct-04-so

4.3 External Crystal Oscillator Circuit

Either a prepackaged oscillator or a simple oscillator circuit with TTL gates can be used as an external crystal oscillator circuit. Prepackaged oscillators provide a wide operating range and better stability. A well-designed crystal oscillator will provide good performance with TTL gates. Two types of crystal oscillator circuits can be used: one with parallel resonance, or one with series resonance.

Figure 4-3 shows an implementation example of a parallel resonant oscillator circuit. The circuit is designed to use the fundamental frequency of the crystal. The 74AS04 inverter performs the 180-degree phase shift that a parallel oscillator requires. The 4.7 kΩ resistor provides the negative feedback for stability. The 10 kΩ potentiometers bias the 74AS04 in the linear region. This circuit could be used for external oscillator designs.

FIGURE 4-3: EXAMPLE OF EXTERNAL PARALLEL RESONANT CRYSTAL OSCILLATOR CIRCUIT (USING XT, HS OR LP OSCILLATOR MODE)

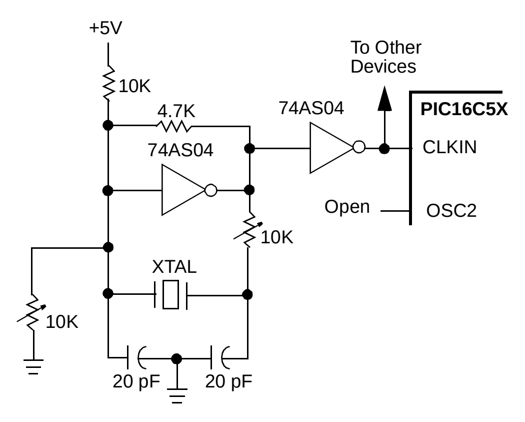
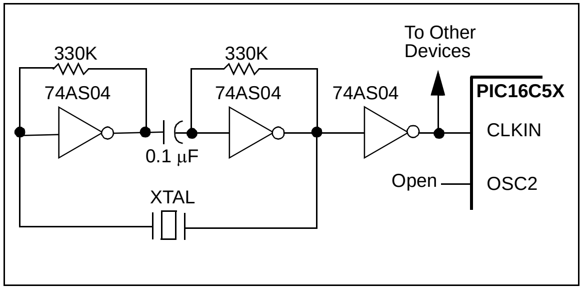


Figure 4-4 shows a series resonant oscillator circuit. This circuit is also designed to use the fundamental frequency of the crystal. The inverter performs a 180-degree phase shift in a series resonant oscillator circuit. The 330 kΩ resistors provide the negative feedback to bias the inverters in their linear region.

FIGURE 4-4: EXAMPLE OF EXTERNAL SERIES RESONANT CRYSTAL OSCILLATOR CIRCUIT (USING XT, HS OR LP OSCILLATOR MODE)



5.0 RESET

PIC16C5X devices may be RESET in one of the following ways:

- Power-On Reset (POR)
- $\overline{\text{MCLR}}$ Reset (normal operation)
- $\overline{\text{MCLR}}$ Wake-up Reset (from SLEEP)
- WDT Reset (normal operation)
- WDT Wake-up Reset (from SLEEP)

Table 5-1 shows these RESET conditions for the PCL and STATUS registers.

Some registers are not affected in any RESET condition. Their status is unknown on POR and unchanged in any other RESET. Most other registers are reset to a “RESET state” on Power-On Reset (POR), $\overline{\text{MCLR}}$ or WDT Reset. A $\overline{\text{MCLR}}$ or WDT wake-up from SLEEP also results in a device RESET, and not a continuation of operation before SLEEP.

The $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits (STATUS <4:3>) are set or cleared depending on the different RESET conditions (Table 5-1). These bits may be used to determine the nature of the RESET.

Table 5-3 lists a full description of RESET states of all registers. Figure 5-1 shows a simplified block diagram of the On-chip Reset circuit.

TABLE 5-1: STATUS BITS AND THEIR SIGNIFICANCE

Condition	$\overline{\text{TO}}$	$\overline{\text{PD}}$
Power-On Reset	`1`	`1`
$\overline{\text{MCLR}}$ Reset (normal operation)	`u`	`u`
$\overline{\text{MCLR}}$ Wake-up (from SLEEP)	`1`	`0`
WDT Reset (normal operation)	`0`	`1`
WDT Wake-up (from SLEEP)	`0`	`0`

Legend: u = unchanged, x = unknown, – = unimplemented read as '0'.

TABLE 5-2: SUMMARY OF REGISTERS ASSOCIATED WITH RESET

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	Value on $\overline{\text{MCLR}}$ and WDT Reset
03h	STATUS	PA2	PA1	PA0	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Z	DC	C	`0001 1xxx`	`000q quuu`

Legend: u = unchanged, x = unknown, q = see Table 5-1 for possible values.

5.1 Power-On Reset (POR)

The PIC16C5X family incorporates on-chip Power-On Reset (POR) circuitry which provides an internal chip RESET for most power-up situations. To use this feature, the user merely ties the $\overline{\text{MCLR}}$/VPP pin to VDD. A simplified block diagram of the on-chip Power-On Reset circuit is shown in Figure 5-1.

The Power-On Reset circuit and the Device Reset Timer (Section 5.2) circuit are closely related. On power-up, the RESET latch is set and the DRT is RESET. The DRT timer begins counting once it detects $\overline{\text{MCLR}}$ to be high. After the time-out period, which is typically 18 ms, it will RESET the reset latch and thus end the on-chip RESET signal.

A power-up example where $\overline{\text{MCLR}}$ is not tied to VDD is shown in Figure 5-3. VDD is allowed to rise and stabilize before bringing $\overline{\text{MCLR}}$ high. The chip will actually come out of reset TDRT msec after $\overline{\text{MCLR}}$ goes high.

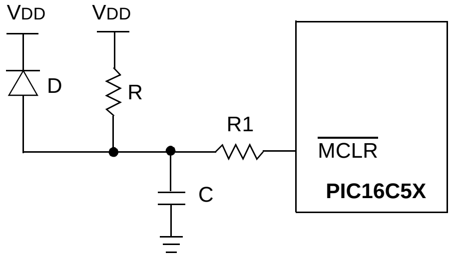
In Figure 5-4, the on-chip Power-On Reset feature is being used ($\overline{\text{MCLR}}$ and VDD are tied together). The VDD is stable before the start-up timer times out and there is no problem in getting a proper RESET. However, Figure 5-5 depicts a problem situation where VDD rises too slowly. The time between when the DRT senses a high on the $\overline{\text{MCLR}}$/VPP pin, and when the $\overline{\text{MCLR}}$/VPP pin (and VDD) actually reach their full value, is too long. In this situation, when the start-up timer times out, VDD has not reached the VDD (min) value and the chip is, therefore, not guaranteed to function correctly. For such situations, we recommend that external RC circuits be used to achieve longer POR delay times (Figure 5-2).

Note:	When the device starts normal operation (exits the RESET condition), device operating parameters (voltage, frequency, temperature, etc.) must be met to ensure operation. If these conditions are not met, the device must be held in RESET until the operating conditions are met.

For more information on PIC16C5X POR, see *Power-Up Considerations* - AN522 in the Embedded Control Handbook.

The POR circuit does not produce an internal RESET when VDD declines.

FIGURE 5-2: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)



- External Power-On Reset circuit is required only if VDD power-up is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.
- R < 40 kΩ is recommended to make sure that voltage drop across R does not violate the device electrical specification.
- R1 = 100Ω to 1 kΩ will limit any current flowing into $\overline{\text{MCLR}}$ from external capacitor C in the event of $\overline{\text{MCLR}}$ pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS).

7.0 I/O PORTS

As with any other register, the I/O Registers can be written and read under program control. However, read instructions (e.g., `MOVF PORTB,W`) always read the I/O pins independent of the pin's input/output modes. On RESET, all I/O ports are defined as input (inputs are at hi-impedance) since the I/O control registers (TRISA, TRISB, TRISC) are all set.

7.1 PORTA

PORTA is a 4-bit I/O Register. Only the low order 4 bits are used (RA<3:0>). Bits 7-4 are unimplemented and read as '0's.

7.2 PORTB

PORTB is an 8-bit I/O Register (PORTB<7:0>).

7.3 PORTC

PORTC is an 8-bit I/O Register for PIC16C55, PIC16C57 and PIC16CR57.

PORTC is a General Purpose Register for PIC16C54, PIC16CR54, PIC16C56, PIC16CR56, PIC16C58 and PIC16CR58.

7.4 TRIS Registers

The Output Driver Control Registers are loaded with the contents of the W Register by executing the `TRIS f` instruction. A '1' from a TRIS Register bit puts the corresponding output driver in a hi-impedance (input) mode. A '0' puts the contents of the output data latch on the selected pins, enabling the output buffer.

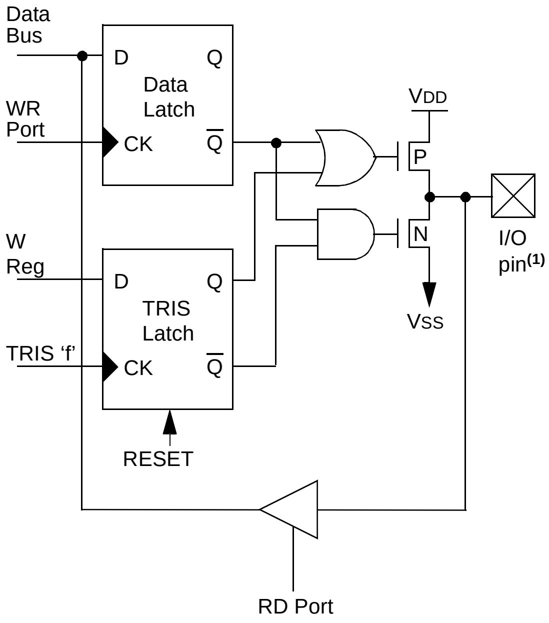
Note: A read of the ports reads the pins, not the output data latches. That is, if an output driver on a pin is enabled and driven high, but the external system is holding it low, a read of the port will indicate that the pin is low.

The TRIS Registers are "write-only" and are set (output drivers disabled) upon RESET.

7.5 I/O Interfacing

The equivalent circuit for an I/O port pin is shown in Figure 7-1. All ports may be used for both input and output operation. For input operations these ports are non-latching. Any input must be present until read by an input instruction (e.g., `MOVF PORTB, W`). The outputs are latched and remain unchanged until the output latch is rewritten. To use a port pin as output, the corresponding direction control bit (in TRISA, TRISB, TRISC) must be cleared (= 0). For use as an input, the corresponding TRIS bit must be set. Any I/O pin can be programmed individually as input or output.

FIGURE 7-1: EQUIVALENT CIRCUIT FOR A SINGLE I/O PIN



Note 1: I/O pins have protection diodes to VDD and VSS.

TABLE 7-1: SUMMARY OF PORT REGISTERS

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-On Reset	Value on $\overline{\text{MCLR}}$ and WDT Reset
N/A	TRIS	I/O Control Registers (TRISA, TRISB, TRISC)								1111 1111	1111 1111
05h	PORTA	—	—	—	—	RA3	RA2	RA1	RA0	---- xxxx	---- uuuu
06h	PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx xxxx	uuuu uuuu
07h	PORTC	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	xxxx xxxx	uuuu uuuu

Legend: x = unknown, u = unchanged, — = unimplemented, read as '0', Shaded cells = unimplemented, read as '0'

NOTES:

10.0 INSTRUCTION SET SUMMARY

Each PIC16C5X instruction is a 12-bit word divided into an OPCODE, which specifies the instruction type and one or more operands which further specify the operation of the instruction. The PIC16C5X instruction set summary in Table 10-2 groups the instructions into byte-oriented, bit-oriented, and literal and control operations. Table 10-1 shows the opcode field descriptions.

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator is used to specify which one of the 32 file registers in that bank is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator which selects the number of the bit affected by the operation, while 'f' represents the number of the file in which the bit is located.

For **literal and control** operations, 'k' represents an 8 or 9-bit constant or literal value.

TABLE 10-1: OPCODE FIELD DESCRIPTIONS

Field	Description
`f`	Register file address (0x00 to 0x1F)
`W`	Working register (accumulator)
`b`	Bit address within an 8-bit file register
`k`	Literal field, constant data or label
`x`	Don't care location (= 0 or 1) The assembler will generate code with x = 0. It is the recommended form of use for compatibility with all Microchip software tools.
`d`	Destination select; d = 0 (store result in W) d = 1 (store result in file register 'f') Default is d = 1
`label`	Label name
`TOS`	Top of Stack
`PC`	Program Counter
`WDT`	Watchdog Timer Counter
$\overline{\mathtt{TO}}$	Time-out bit
$\overline{\mathtt{PD}}$	Power-down bit
`dest`	Destination, either the W register or the specified register file location
`[ ]`	Options
`( )`	Contents
→	Assigned to
`< >`	Register bit field
∈	In the set of
`italics`	User defined term (font is courier)

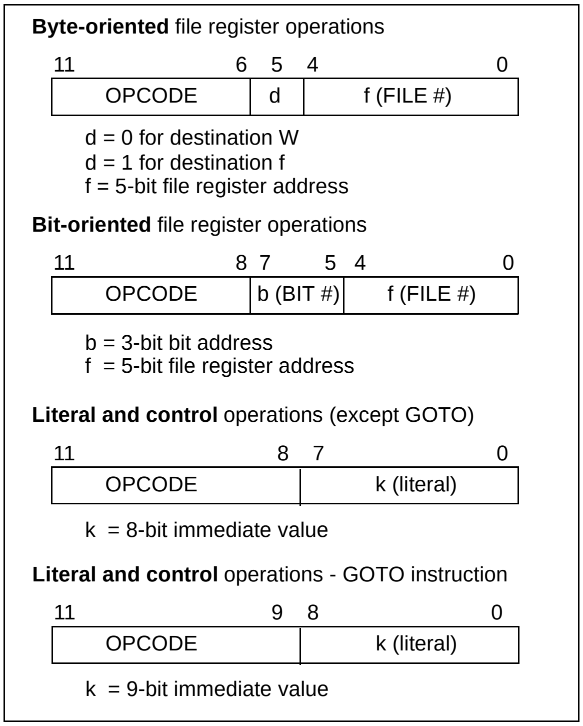
All instructions are executed within one single instruction cycle, unless a conditional test is true or the program counter is changed as a result of an instruction. In this case, the execution takes two instruction cycles. One instruction cycle consists of four oscillator periods. Thus, for an oscillator frequency of 4 MHz, the normal instruction execution time would be 1 μs. If a conditional test is true or the program counter is changed as a result of an instruction, the instruction execution time would be 2 μs.

Figure 10-1 shows the three general formats that the instructions can have. All examples in the figure use the following format to represent a hexadecimal number:

0xhhh

where 'h' signifies a hexadecimal digit.

FIGURE 10-1: GENERAL FORMAT FOR INSTRUCTIONS



Byte-oriented file register operations

d = 0 for destination W
d = 1 for destination f
f = 5-bit file register address

Bit-oriented file register operations

b = 3-bit bit address
f = 5-bit file register address

Literal and control operations (except GOTO)

k = 8-bit immediate value

Literal and control operations - GOTO instruction

k = 9-bit immediate value

IORLW **Inclusive OR literal with W**

Syntax:	[*label*] IORLW k
Operands:	0 ≤ k ≤ 255
Operation:	(W) .OR. (k) → (W)
Status Affected:	Z
Encoding:	`1101` `kkkk` `kkkk`
Description:	The contents of the W register are OR’ed with the eight bit literal 'k'. The result is placed in the W register.
Words:	1
Cycles:	1
Example:	`IORLW` 0x35

Before Instruction
W = 0x9A
After Instruction
W = 0xBF
Z = 0

IORWF **Inclusive OR W with f**

Syntax:	[*label*] IORWF f,d
Operands:	0 ≤ f ≤ 31 d ∈ [0,1]
Operation:	(W).OR. (f) → (dest)
Status Affected:	Z
Encoding:	`0001` `00df` `ffff`
Description:	Inclusive OR the W register with register 'f'. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.
Words:	1
Cycles:	1
Example:	`IORWF RESULT, 0`

Before Instruction
RESULT = 0x13
W = 0x91
After Instruction
RESULT = 0x13
W = 0x93
Z = 0

MOVF **Move f**

Syntax:	[*label*] MOVF f,d
Operands:	0 ≤ f ≤ 31 d ∈ [0,1]
Operation:	(f) → (dest)
Status Affected:	Z
Encoding:	`0010` `00df` `ffff`
Description:	The contents of register 'f' is moved to destination 'd'. If 'd' is 0, destination is the W register. If 'd' is 1, the destination is file register 'f'. 'd' is 1 is useful to test a file register since status flag Z is affected.
Words:	1
Cycles:	1
Example:	`MOVF FSR, 0`

After Instruction
W = value in FSR register

MOVLW **Move Literal to W**

Syntax:	[*label*] MOVLW k
Operands:	0 ≤ k ≤ 255
Operation:	k → (W)
Status Affected:	None
Encoding:	`1100` `kkkk` `kkkk`
Description:	The eight bit literal 'k' is loaded into the W register.
Words:	1
Cycles:	1
Example:	`MOVLW` 0x5A

After Instruction
W = 0x5A

12.3 DC Characteristics: PIC16C54/55/56/57-RCE, XTE, 10E, HSE, LPE (Extended)

PIC16C54/55/56/57-RCE, XTE, 10E, HSE, LPE (Extended)			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature –40°C ≤ TA ≤ +125°C for extended				
Param No.	**Symbol**	**Characteristic/Device**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	VDD	**Supply Voltage** PIC16C5X-RCE PIC16C5X-XTE PIC16C5X-10E PIC16C5X-HSE PIC16C5X-LPE	 3.25 3.25 4.5 4.5 2.5	 — — — — —	 6.0 6.0 5.5 5.5 6.0	 V V V V V	
D002	VDR	**RAM Data Retention Voltage**(1)	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	**VDD Start Voltage** to ensure Power-on Reset	—	VSS	—	V	See Section 5.1 for details on Power-on Reset
D004	SVDD	**VDD Rise Rate** to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset
D010	IDD	**Supply Current**(2) PIC16C5X-RCE(3) PIC16C5X-XTE PIC16C5X-10E PIC16C5X-HSE PIC16C5X-HSE PIC16C5X-LPE	 — — — — — —	 1.8 1.8 4.8 4.8 9.0 19	 3.3 3.3 10 10 20 55	 mA mA mA mA mA μA	 FOSC = 4 MHz, VDD = 5.5V FOSC = 4 MHz, VDD = 5.5V FOSC = 10 MHz, VDD = 5.5V FOSC = 10 MHz, VDD = 5.5V FOSC = 16 MHz, VDD = 5.5V FOSC = 32 kHz, VDD = 3.25V, WDT disabled
D020	IPD	**Power-down Current**(2)	— —	5.0 0.8	22 18	μA μA	VDD = 3.25V, WDT enabled VDD = 3.25V, WDT disabled

* These parameters are characterized but not tested.

† Data in "Typ" column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, $\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

13.3 DC Characteristics: PIC16CR54A-04, 10, 20, PIC16LCR54A-04 (Commercial) PIC16CR54A-04I, 10I, 20I, PIC16LCR54A-04I (Industrial)

DC CHARACTERISTICS			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D030	VIL	**Input Low Voltage**					
		I/O ports	VSS	—	0.2 VDD	V	Pin at hi-impedance
		$\overline{\text{MCLR}}$ (Schmitt Trigger)	VSS	—	0.15 VDD	V	
		T0CKI (Schmitt Trigger)	VSS	—	0.15 VDD	V	
		OSC1 (Schmitt Trigger)	VSS	—	0.15 VDD	V	RC mode only(3)
		OSC1	VSS	—	0.15 VDD	V	XT, HS and LP modes
D040	VIH	**Input High Voltage**					
		I/O ports	2.0	—	VDD	V	VDD = 3.0V to 5.5V(4)
		I/O ports	0.6 VDD	—	VDD	V	Full VDD range(4)
		$\overline{\text{MCLR}}$ (Schmitt Trigger)	0.85 VDD	—	VDD	V	
		T0CKI (Schmitt Trigger)	0.85 VDD	—	VDD	V	
		OSC1 (Schmitt Trigger)	0.85 VDD	—	VDD	V	RC mode only(3)
		OSC1	0.85 VDD	—	VDD	V	XT, HS and LP modes
D050	VHYS	**Hysteresis of Schmitt Trigger inputs**	0.15 VDD*	—	—	V	
D060	IIL	**Input Leakage Current(1,2)**					**For VDD ≤ 5.5V:**
		I/O ports	–1.0	—	+1.0	μA	VSS ≤ VPIN ≤ VDD, pin at hi-impedance
		MCLR	–5.0	—	—	μA	VPIN = VSS + 0.25V
		MCLR	—	0.5	+5.0	μA	VPIN = VDD
		T0CKI	–3.0	0.5	+3.0	μA	VSS ≤ VPIN ≤ VDD
		OSC1	–3.0	0.5	+3.0	μA	VSS ≤ VPIN ≤ VDD, XT, HS and LP modes
D080	VOL	**Output Low Voltage**					
		I/O ports	—	—	0.5	V	IOL = 10 mA, VDD = 6.0V
		OSC2/CLKOUT	—	—	0.5	V	IOL = 1.9 mA, VDD = 6.0V, RC mode only
D090	VOH	**Output High Voltage(2)**					
		I/O ports	VDD – 0.5	—	—	V	IOH = –4.0 mA, VDD = 6.0V
		OSC2/CLKOUT	VDD – 0.5	—	—	V	IOH = –0.8 mA, VDD = 6.0V, RC mode only

* These parameters are characterized but not tested.

† Data in the Typical (“Typ”) column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: The leakage current on the $\overline{\text{MCLR}}$/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.

2: Negative current is defined as coming out of the pin.

3: For the RC mode, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C5X be driven with external clock in RC mode.

4: The user may use the better of the two specifications.

FIGURE 14-4: TYPICAL RC OSC FREQUENCY vs. VDD, CEXT = 300 PF

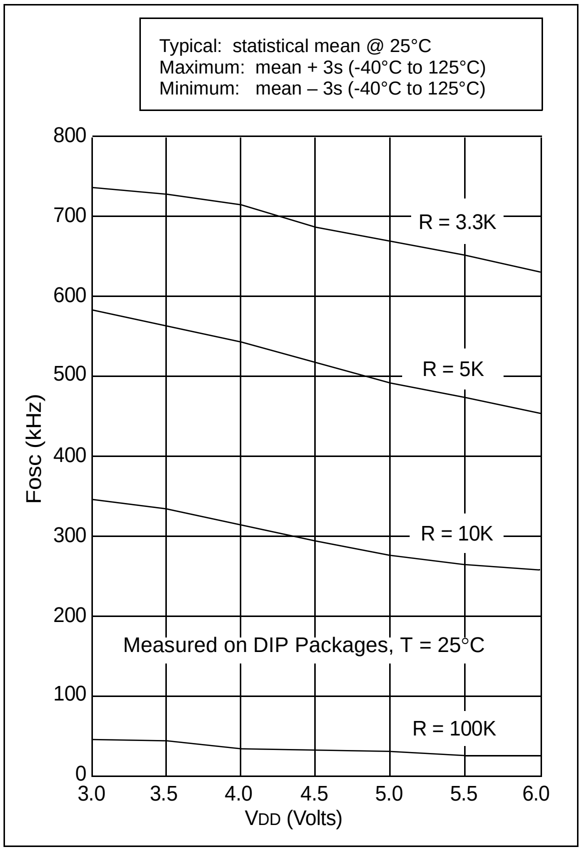


FIGURE 14-5: TYPICAL IPD vs. VDD, WATCHDOG DISABLED

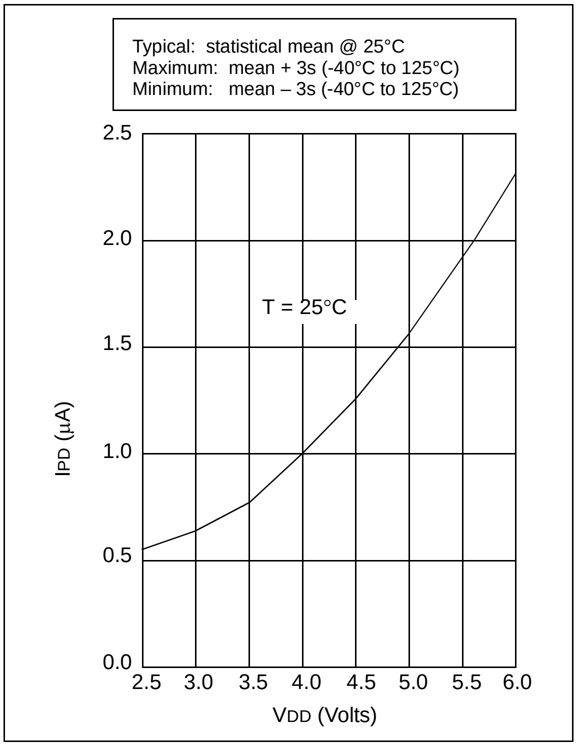


FIGURE 14-19: PORTA, B AND C IOH vs. VOH, VDD = 3 V

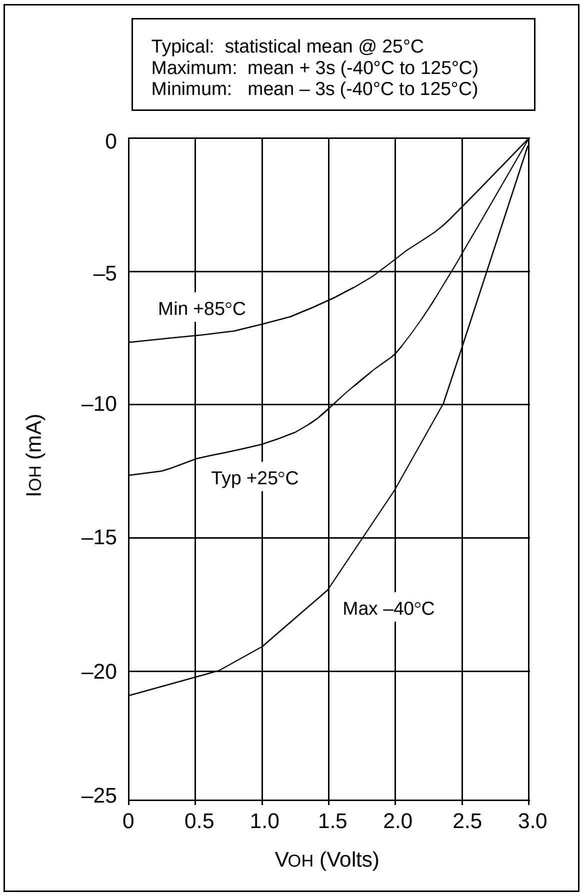


FIGURE 14-20: PORTA, B AND C IOH vs. VOH, VDD = 5 V

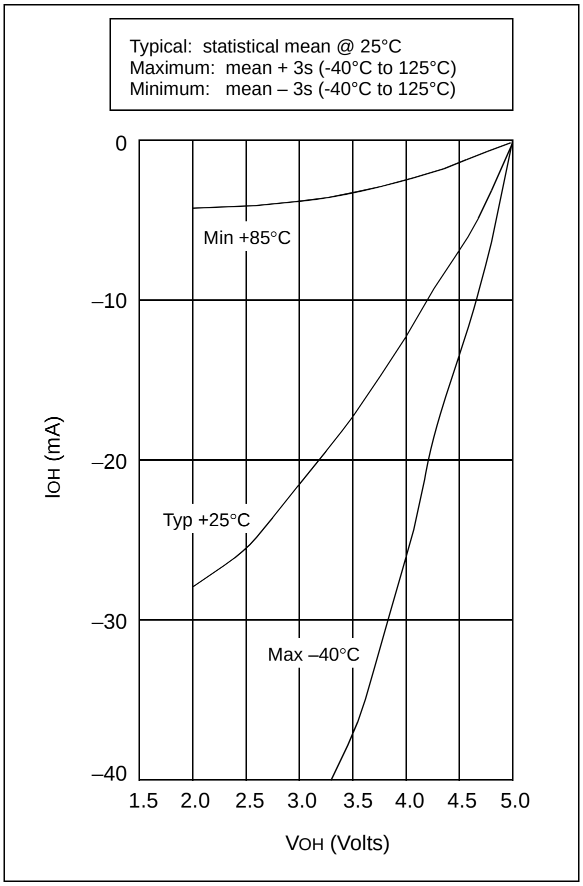
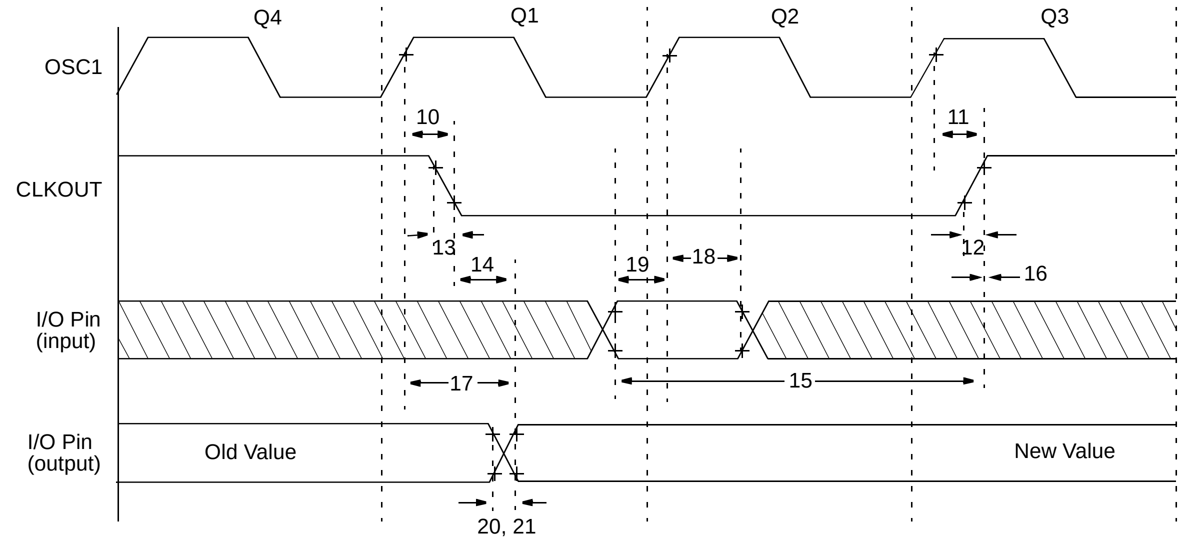


FIGURE 15-3: CLKOUT AND I/O TIMING - PIC16C54A



Note: Please refer to Figure 15-1 for load conditions.

TABLE 15-2: CLKOUT AND I/O TIMING REQUIREMENTS - PIC16C54A

AC Characteristics	**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial –20°C ≤ TA ≤ +85°C for industrial - PIC16LV54A-02I –40°C ≤ TA ≤ +125°C for extended

Param No.	Symbol	Characteristic	Min	Typ†	Max	Units
10	TosH2ckL	OSC1↑ to CLKOUT↓(1)	—	15	30**	ns
11	TosH2ckH	OSC1↑ to CLKOUT↑(1)	—	15	30**	ns
12	TckR	CLKOUT rise time(1)	—	5.0	15**	ns
13	TckF	CLKOUT fall time(1)	—	5.0	15**	ns
14	TckL2ioV	CLKOUT↓ to Port out valid(1)	—	—	40**	ns
15	TioV2ckH	Port in valid before CLKOUT↑(1)	0.25 TCY+30*	—	—	ns
16	TckH2ioI	Port in hold after CLKOUT↑(1)	0*	—	—	ns
17	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid(2)	—	—	100*	ns
18	TosH2ioI	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	TBD	—	—	ns
19	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	TBD	—	—	ns
20	TioR	Port output rise time(2)	—	10	25**	ns
21	TioF	Port output fall time(2)	—	10	25**	ns

* These parameters are characterized but not tested.

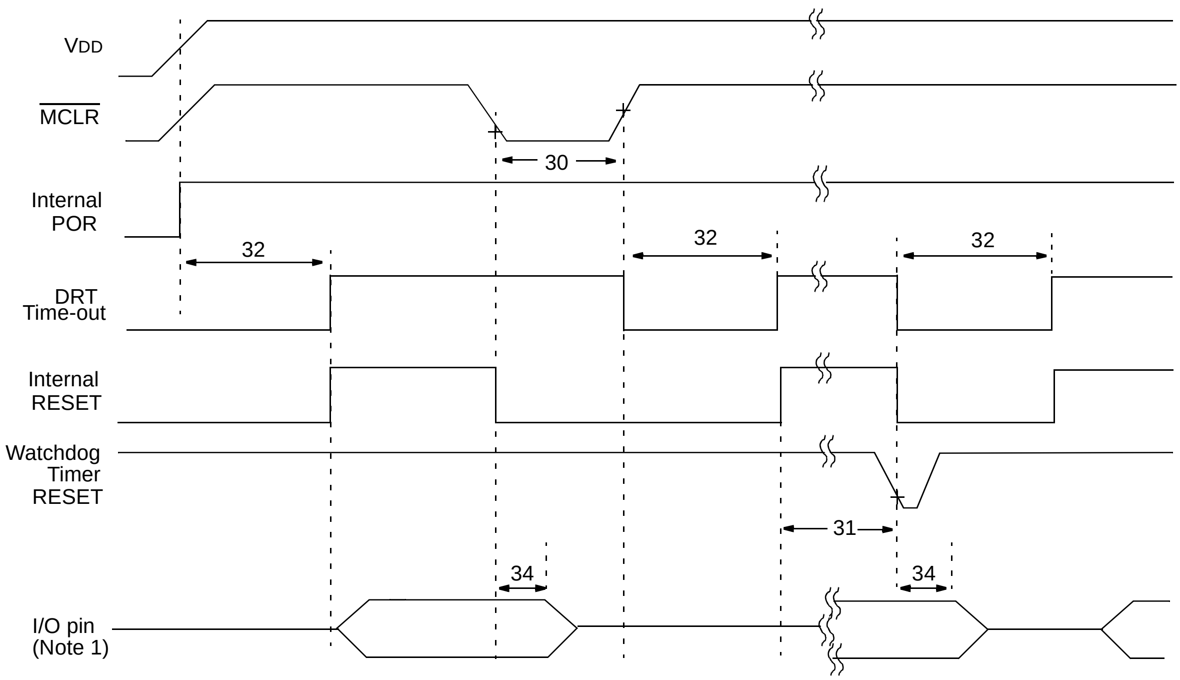
** These parameters are design targets and are not tested. No characterization data available at this time.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x TOSC.

2: Please refer to Figure 15-1 for load conditions.

FIGURE 15-4: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER TIMING - PIC16C54A



Note 1: Please refer to Figure 15-1 for load conditions.

TABLE 15-3: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER - PIC16C54A

<table>
<tr><td colspan="2">AC Characteristics</td><td colspan="6">Standard Operating Conditions (unless otherwise specified)
Operating Temperature 0°C ≤ TA ≤ +70°C for commercial
–40°C ≤ TA ≤ +85°C for industrial
–20°C ≤ TA ≤ +85°C for industrial - PIC16LV54A-02I
–40°C ≤ TA ≤ +125°C for extended</td></tr>
<tr><th>Param No.</th><th>Symbol</th><th>Characteristic</th><th>Min</th><th>Typ†</th><th>Max</th><th>Units</th><th>Conditions</th></tr>
<tr><td>30</td><td>TmcL</td><td>$\overline{\text{MCLR}}$ Pulse Width (low)</td><td>100*
1</td><td>—
—</td><td>—
—</td><td>ns
µs</td><td>VDD = 5.0V
VDD = 5.0V (PIC16LV54A only)</td></tr>
<tr><td>31</td><td>Twdt</td><td>Watchdog Timer Time-out Period (No Prescaler)</td><td>9.0*</td><td>18*</td><td>30*</td><td>ms</td><td>VDD = 5.0V (Comm)</td></tr>
<tr><td>32</td><td>TDRT</td><td>Device Reset Timer Period</td><td>9.0*</td><td>18*</td><td>30*</td><td>ms</td><td>VDD = 5.0V (Comm)</td></tr>
<tr><td>34</td><td>Tioz</td><td>I/O Hi-impedance from $\overline{\text{MCLR}}$ Low</td><td>—
—</td><td>—
—</td><td>100*
1µs</td><td>ns
—</td><td>
(PIC16LV54A only)</td></tr>
</table>

* These parameters are characterized but not tested.

† Data in the Typical (“Typ”) column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

16.0 DEVICE CHARACTERIZATION - PIC16C54A

The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

"Typical" represents the mean of the distribution at 25°C. "Maximum" or "minimum" represents (mean + 3σ) or (mean – 3σ) respectively, where σ is a standard deviation, over the whole temperature range.

FIGURE 16-1: TYPICAL RC OSCILLATOR FREQUENCY vs. TEMPERATURE

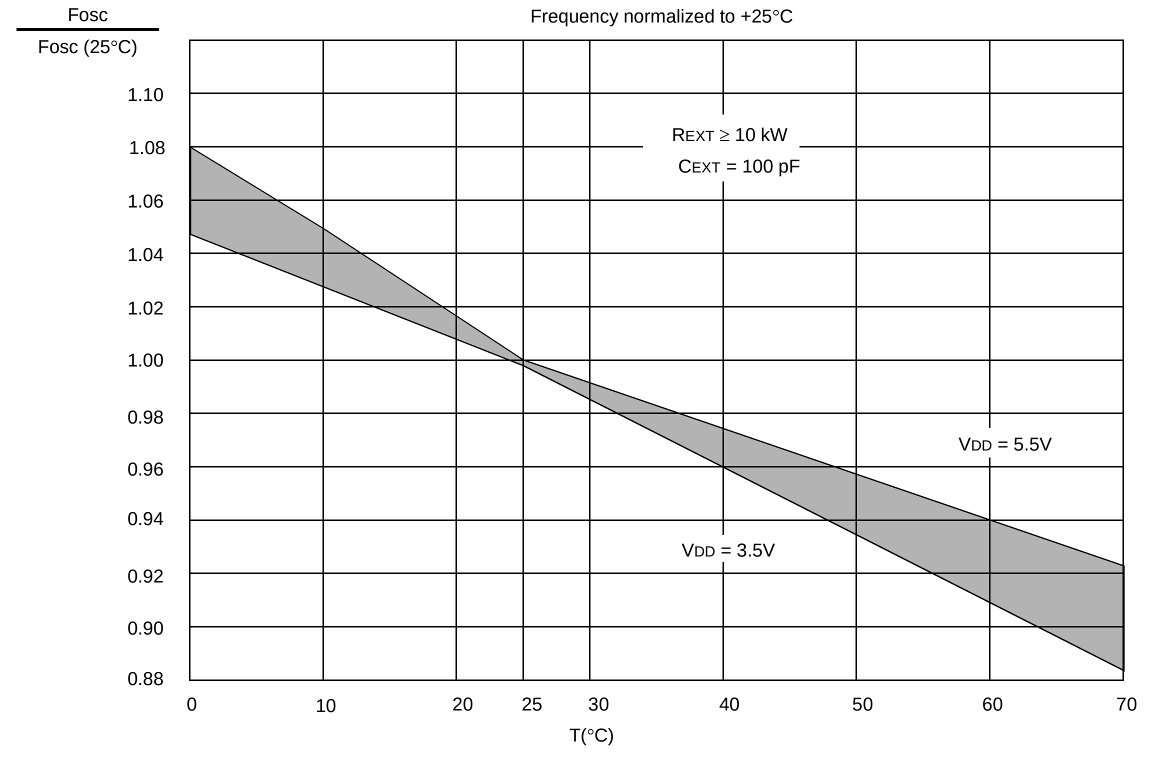


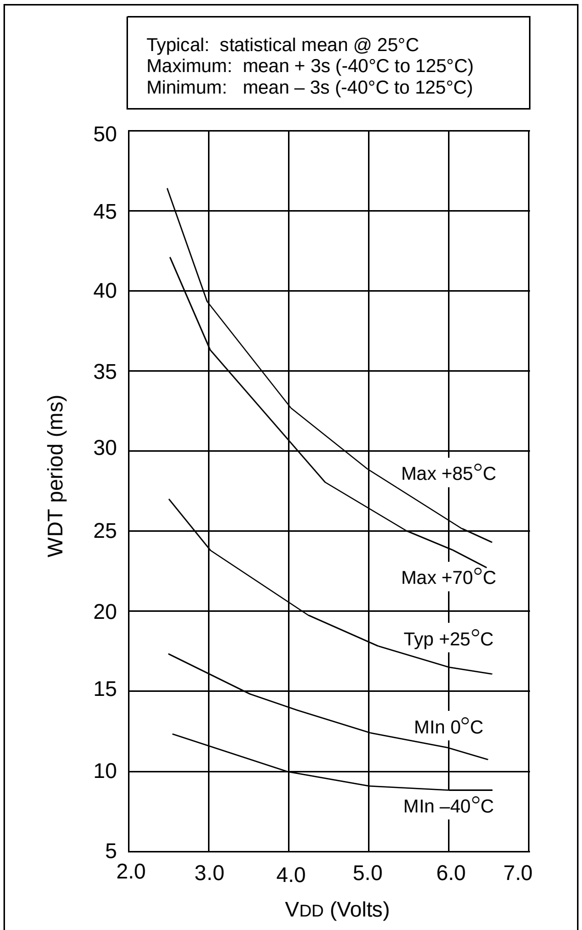
TABLE 16-1: RC OSCILLATOR FREQUENCIES

CEXT	REXT	Average Fosc @ 5 V, 25°C	
20 pF	3.3K	5 MHz	± 27%
	5K	3.8 MHz	± 21%
	10K	2.2 MHz	± 21%
	100K	262 kHz	± 31%
100 pF	3.3K	1.6 MHz	± 13%
	5K	1.2 MHz	± 13%
	10K	684 kHz	± 18%
	100K	71 kHz	± 25%
300 pF	3.3K	660 kHz	± 10%
	5.0K	484 kHz	± 14%
	10K	267 kHz	± 15%
	100K	29 kHz	± 19%

The frequencies are measured on DIP packages.

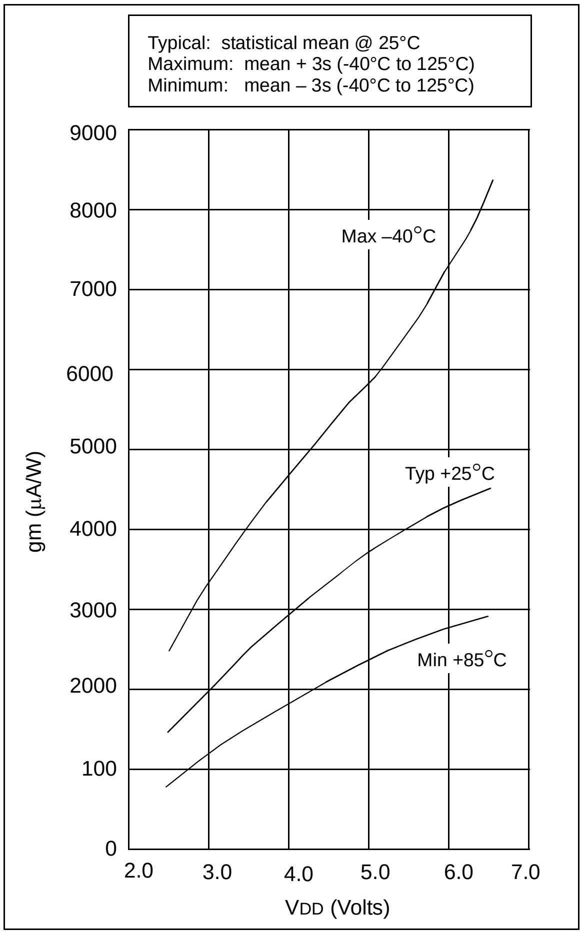
The percentage variation indicated here is part-to-part variation due to normal process distribution. The variation indicated is ±3 standard deviation from average value for VDD = 5V.

FIGURE 16-16: WDT TIMER TIME-OUT PERIOD vs. VDD(1)



Note 1: Prescaler set to 1:1.

FIGURE 16-17: TRANSCONDUCTANCE (gm) OF HS OSCILLATOR vs. VDD



17.1 DC Characteristics: PIC16C54C/C55A/C56A/C57C/C58B-04, 20 (Commercial, Industrial) PIC16LC54C/LC55A/LC56A/LC57C/LC58B-04 (Commercial, Industrial) PIC16CR54C/CR56A/CR57C/CR58B-04, 20 (Commercial, Industrial) PIC16LCR54C/LCR56A/LCR57C/LCR58B-04 (Commercial, Industrial)

PIC16LC5X **PIC16LCR5X** (Commercial, Industrial)	**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial
PIC16C5X **PIC16CR5X** (Commercial, Industrial)	**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial

Param No.	Symbol	Characteristic/Device	Min	Typ†	Max	Units	Conditions
	IDD	**Supply Current[2,3]**					
D010		PIC16LC5X	—	0.5	2.4	mA	FOSC = 4.0 MHz, VDD = 5.5V, XT and RC modes
			—	11	27	µA	FOSC = 32 kHz, VDD = 2.5V, LP mode, Commercial
			—	14	35	µA	FOSC = 32 kHz, VDD = 2.5V, LP mode, Industrial
D010A		PIC16C5X	—	1.8	2.4	mA	FOSC = 4 MHz, VDD = 5.5V, XT and RC modes
			—	2.6	3.6*	mA	FOSC = 10 MHz, VDD = 3.0V, HS mode
			—	4.5	16	mA	FOSC = 20 MHz, VDD = 5.5V, HS mode
			—	14	32	µA	FOSC = 32 kHz, VDD = 3.0V, LP mode, Commercial
			—	17	40	µA	FOSC = 32 kHz, VDD = 3.0V, LP mode, Industrial

Legend: Rows with standard voltage device data only are shaded for improved readability.

* These parameters are characterized but not tested.

† Data in “Typ” column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only, and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

17.3 DC Characteristics: PIC16C54C/C55A/C56A/C57C/C58B-04, 20 (Commercial, Industrial, Extended)
PIC16LC54C/LC55A/LC56A/LC57C/LC58B-04 (Commercial, Industrial)
PIC16CR54C/CR56A/CR57C/CR58B-04, 20 (Commercial, Industrial, Extended)
PIC16LCR54C/LCR56A/LCR57C/LCR58B-04 (Commercial, Industrial)

<table>
<tr><td colspan="3">DC CHARACTERISTICS</td><td colspan="5">Standard Operating Conditions (unless otherwise specified)
Operating Temperature 0°C ≤ TA ≤ +70°C for commercial
–40°C ≤ TA ≤ +85°C for industrial
–40°C ≤ TA ≤ +125°C for extended</td></tr>
<tr><th>Param No.</th><th>Symbol</th><th>Characteristic</th><th>Min</th><th>Typ†</th><th>Max</th><th>Units</th><th>Conditions</th></tr>
<tr><td>D030</td><td>VIL</td><td>Input Low Voltage</td><td></td><td></td><td></td><td></td><td></td></tr>
<tr><td></td><td></td><td>I/O Ports</td><td>VSS</td><td>—</td><td>0.8 V</td><td>V</td><td>4.5V <VDD ≤ 5.5V</td></tr>
<tr><td></td><td></td><td>I/O Ports</td><td>VSS</td><td>—</td><td>0.15 VDD</td><td>V</td><td>Otherwise</td></tr>
<tr><td></td><td></td><td>$\overline{\text{MCLR}}$ (Schmitt Trigger)</td><td>VSS</td><td>—</td><td>0.15 VDD</td><td>V</td><td></td></tr>
<tr><td></td><td></td><td>T0CKI (Schmitt Trigger)</td><td>VSS</td><td>—</td><td>0.15 VDD</td><td>V</td><td></td></tr>
<tr><td></td><td></td><td>OSC1 (Schmitt Trigger)</td><td>VSS</td><td>—</td><td>0.15 VDD</td><td>V</td><td>RC mode only(3)</td></tr>
<tr><td></td><td></td><td>OSC1</td><td>VSS</td><td>—</td><td>0.3 VDD</td><td>V</td><td>XT, HS and LP modes</td></tr>
<tr><td>D040</td><td>VIH</td><td>Input High Voltage</td><td></td><td></td><td></td><td></td><td></td></tr>
<tr><td></td><td></td><td>I/O ports</td><td>2.0</td><td>—</td><td>VDD</td><td>V</td><td>4.5V < VDD ≤ 5.5V</td></tr>
<tr><td></td><td></td><td>I/O ports</td><td>0.25 VDD+0.8</td><td>—</td><td>VDD</td><td>V</td><td>Otherwise</td></tr>
<tr><td></td><td></td><td>$\overline{\text{MCLR}}$ (Schmitt Trigger)</td><td>0.85 VDD</td><td>—</td><td>VDD</td><td>V</td><td></td></tr>
<tr><td></td><td></td><td>T0CKI (Schmitt Trigger)</td><td>0.85 VDD</td><td>—</td><td>VDD</td><td>V</td><td></td></tr>
<tr><td></td><td></td><td>OSC1 (Schmitt Trigger)</td><td>0.85 VDD</td><td>—</td><td>VDD</td><td>V</td><td>RC mode only(3)</td></tr>
<tr><td></td><td></td><td>OSC1</td><td>0.7 VDD</td><td>—</td><td>VDD</td><td>V</td><td>XT, HS and LP modes</td></tr>
<tr><td>D050</td><td>VHYS</td><td>Hysteresis of Schmitt Trigger inputs</td><td>0.15 VDD*</td><td>—</td><td>—</td><td>V</td><td></td></tr>
<tr><td>D060</td><td>IIL</td><td>Input Leakage Current(1,2)</td><td></td><td></td><td></td><td></td><td>For VDD ≤ 5.5V:</td></tr>
<tr><td></td><td></td><td>I/O ports</td><td>-1.0</td><td>0.5</td><td>+1.0</td><td>μA</td><td>VSS ≤ VPIN ≤ VDD,
pin at hi-impedance</td></tr>
<tr><td></td><td></td><td>$\overline{\text{MCLR}}$</td><td>-5.0</td><td>—</td><td>+5.0</td><td>μA</td><td>VPIN = VSS +0.25V</td></tr>
<tr><td></td><td></td><td>$\overline{\text{MCLR}}$</td><td></td><td>0.5</td><td>+3.0</td><td>μA</td><td>VPIN = VDD</td></tr>
<tr><td></td><td></td><td>T0CKI</td><td>-3.0</td><td>0.5</td><td>+3.0</td><td>μA</td><td>VSS ≤ VPIN ≤ VDD</td></tr>
<tr><td></td><td></td><td>OSC1</td><td>-3.0</td><td>0.5</td><td>—</td><td>μA</td><td>VSS ≤ VPIN ≤ VDD,
XT, HS and LP modes</td></tr>
<tr><td>D080</td><td>VOL</td><td>Output Low Voltage</td><td></td><td></td><td></td><td></td><td></td></tr>
<tr><td></td><td></td><td>I/O ports</td><td>—</td><td>—</td><td>0.6</td><td>V</td><td>IOL = 8.7 mA, VDD = 4.5V</td></tr>
<tr><td></td><td></td><td>OSC2/CLKOUT</td><td>—</td><td>—</td><td>0.6</td><td>V</td><td>IOL = 1.6 mA, VDD = 4.5V,
RC mode only</td></tr>
<tr><td>D090</td><td>VOH</td><td>Output High Voltage(2)</td><td></td><td></td><td></td><td></td><td></td></tr>
<tr><td></td><td></td><td>I/O ports</td><td>VDD - 0.7</td><td>—</td><td>—</td><td>V</td><td>IOH = -5.4 mA, VDD = 4.5V</td></tr>
<tr><td></td><td></td><td>OSC2/CLKOUT</td><td>VDD - 0.7</td><td>—</td><td>—</td><td>V</td><td>IOH = -1.0 mA, VDD = 4.5V,
RC mode only</td></tr>
</table>

* These parameters are characterized but not tested.

† Data in the Typical (“Typ”) column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: The leakage current on the $\overline{\text{MCLR}}$/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.

2: Negative current is defined as coming out of the pin.

3: For the RC mode, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C5X be driven with external clock in RC mode.

FIGURE 18-6: TYPICAL IPD vs. VDD, WATCHDOG ENABLED (25°C)

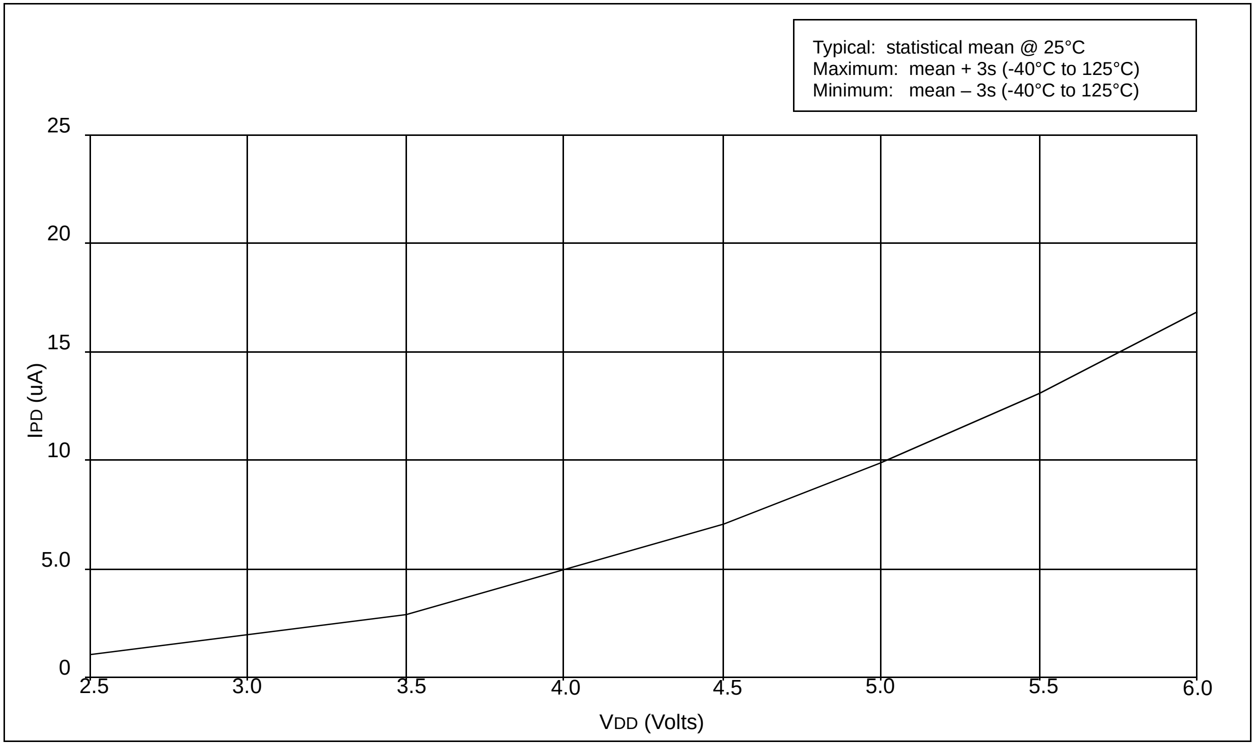


FIGURE 18-7: TYPICAL IPD vs. VDD, WATCHDOG ENABLED (–40°C, 85°C)

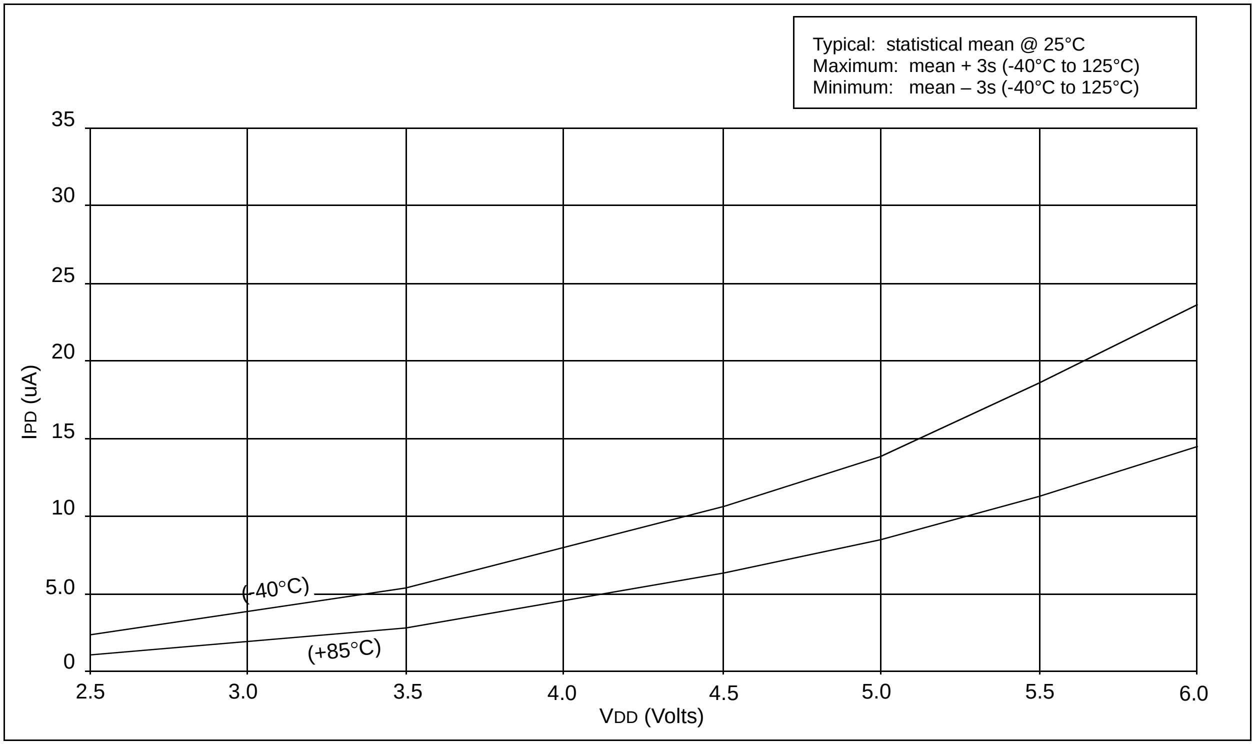
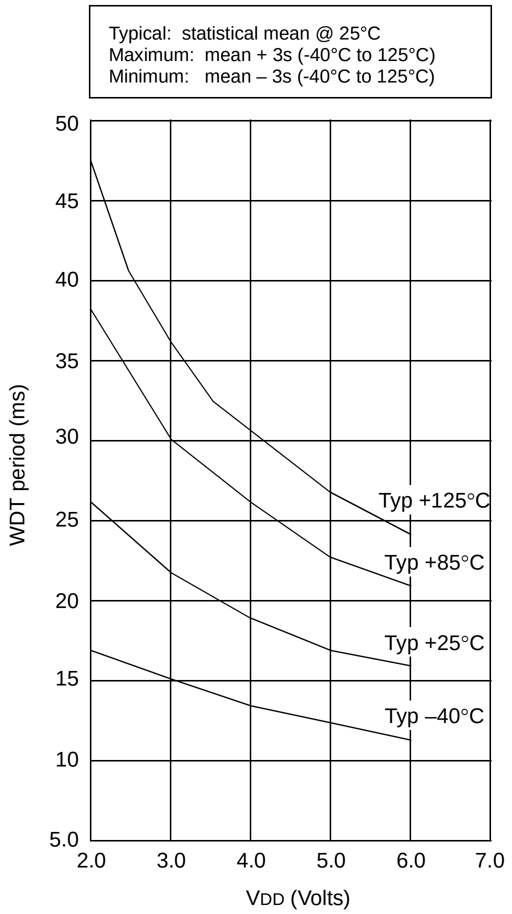


FIGURE 20-7: WDT TIMER TIME-OUT PERIOD vs. VDD(1)



Note 1: Prescaler set to 1:1.

FIGURE 20-8: IOH vs. VOH, VDD = 5 V

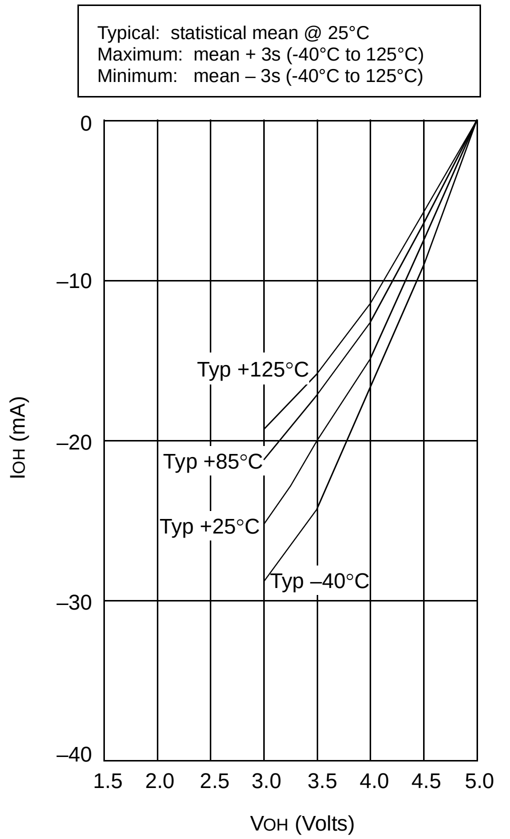


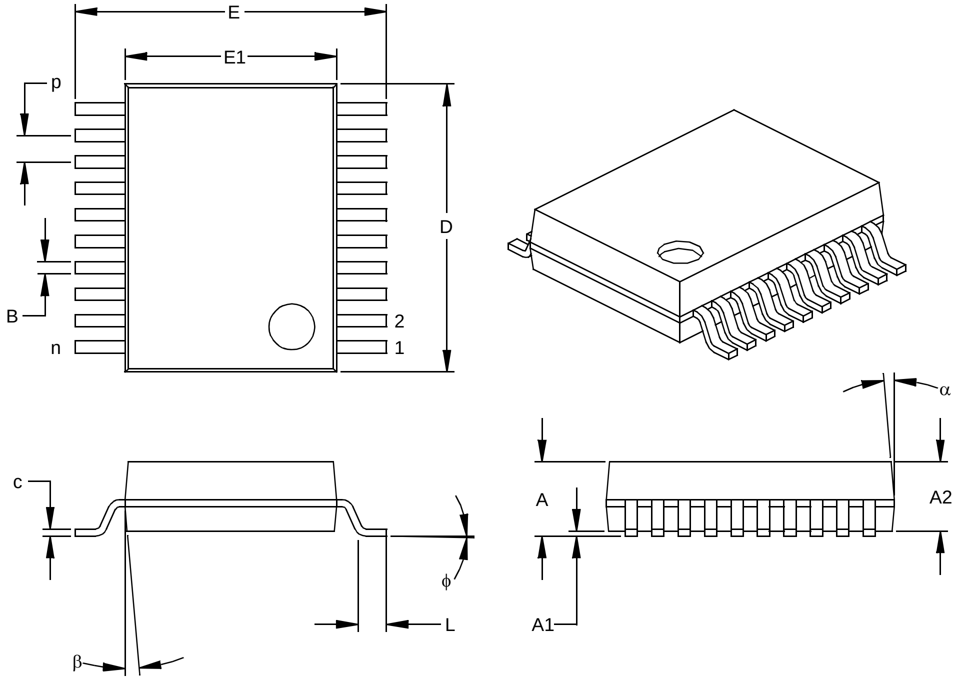
TABLE 20-1: INPUT CAPACITANCE

Pin	Typical Capacitance (pF)	
	18L PDIP	18L SOIC
RA port	5.0	4.3
RB port	5.0	4.3
$\overline{\text{MCLR}}$	17.0	17.0
OSC1	4.0	3.5
OSC2/CLKOUT	4.3	3.5
T0CKI	3.2	2.8

All capacitance values are typical at 25°C. A part-to-part variation of ±25% (three standard deviations) should be taken into account.

20-Lead Plastic Shrink Small Outline (SS) – 209 mil, 5.30 mm (SSOP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	INCHES*			MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		20			20	
Pitch	p		.026			0.65	
Overall Height	A	.068	.073	.078	1.73	1.85	1.98
Molded Package Thickness	A2	.064	.068	.072	1.63	1.73	1.83
Standoff §	A1	.002	.006	.010	0.05	0.15	0.25
Overall Width	E	.299	.309	.322	7.59	7.85	8.18
Molded Package Width	E1	.201	.207	.212	5.11	5.25	5.38
Overall Length	D	.278	.284	.289	7.06	7.20	7.34
Foot Length	L	.022	.030	.037	0.56	0.75	0.94
Lead Thickness	c	.004	.007	.010	0.10	0.18	0.25
Foot Angle	φ	0	4	8	0.00	101.60	203.20
Lead Width	B	.010	.013	.015	0.25	0.32	0.38
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MO-150
Drawing No. C04-072